

承认书

APPROVAL SHEET

产品名称： 多层片式陶瓷电容器

PART NAME: MULTILAYER CERAMI CAPACITORS

系 列 : 中高压系列 (100V~3000V)

SERIES : Mid-High Volts Series (100V~3000V)

规 格 : 0402 ~ 1812 尺寸

SPECIFICATION: 0402 ~ 1812 Size

供 应 商 (SUPPLIER) : 利容

发布日期 (ISSUED DATE) : 20220308

批 准 (APPROVED BY) :

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一、MLCC 简介 General Introduction

片式多层陶瓷电容器（MLCC）是适合于表面贴装技术（SMT）的小尺寸、高比容、高精度陶瓷介质电容器，可贴装于印刷线路板（PCB）、混合集成电路（HIC）基片，有效地缩小电子信息终端产品（尤其是便携式产品）的体积和重量，提高产品可靠性。顺应了IT产业小型化、轻量化、高性能、多功能的发展方向，陶瓷电容器适合厂家高密度、高效表面贴装。

Multi-layer ceramic chip capacitor is a kind of ceramic dielectric capacitor with small size, high capacitance per volume, high accuracy, suited surface mounted technology (SMT). It is widely used in electronic circuitry, mounted printed circuit board, and hybrid IC. These different functions require specific capacitor properties.

二、中高压电容器 High Voltage MLCC

中高压多层片状陶瓷电容器是在多层片状陶瓷电容器的工艺技术、设备基础上，通过采用特殊工艺制作的一种高耐压的可靠性产品，该产品适合于表面贴装，适合于多种直流高压线路，可以有效的改善电子线路的性能。

Middle & high voltage MLCC is a kind of special design 、special technology MLCC that bases on the technology of general MLCC. This kind of MLCC has stable high voltage reliability and suitable to SMT. Middle & high voltage MLCC is widely applicable for many DC high voltage circuits in which it can improve the performance of the circuit.

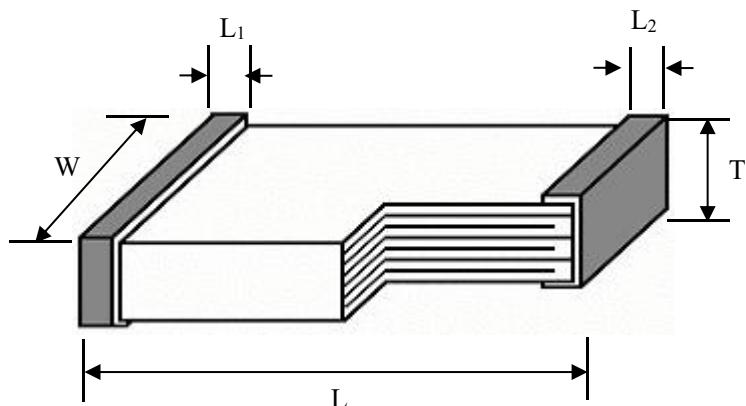
三、中高压产品特点 Features:

- a、产品型号耐高电压。Product model high pressure resistance
- b、高稳定性、高可靠性。 High stability and reliability.

四、中高压应用领域 Applications:

- a、模拟或数字调制解调器 。 Analog & Digital Modems
- b、局域网/广域网接口界面。 LAN/WAN Interface
- c、倍压电器。 Voltage Multipliers
- d、直流变送器。 DC-DC Converters
- e、背光源驱动电路。 Back-lighting Driver

五、MLCC 产品尺寸与结构 MLCC Product Size and Structure



型号 Type		尺寸 Dimensions (mm)			
英制表示 British	公制表示 Metric	L	W	T	L ₁ / L ₂
0402	1005	1.00±0.05	0.50±0.05	0.50±0.05	0.25±0.10
0603	1608	1.60±0.10	0.80±0.10	0.80±0.10	0.30±0.10
0805	2012	2.00±0.20	1.25±0.20	≤0.55 0.80±0.20 1.00±0.20 1.25±0.20	0.50±0.20
1206	3216	3.20±0.30	1.60±0.30	0.80±0.20 1.00±0.20 1.25±0.20 1.60±0.30	0.60±0.30
1210	3225	3.20±0.30	2.50±0.30	≤2.80	0.60±0.30
1812	4532	4.50±0.40	3.20±0.30	≤3.50	0.60±0.30
2220	5750	5.70±0.40	5.00±0.40	≤3.50	0.60±0.30

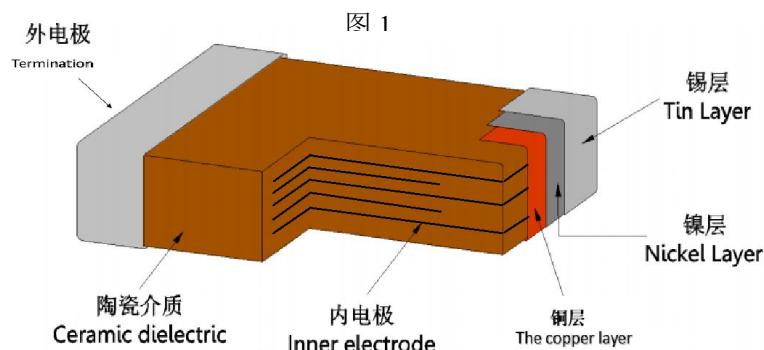


图1 片式多层陶瓷电容器外形与内部结构 Figure 1 Dimension and Cross-section of MLCC

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 利容电子（江门）有限公司
 Lirong electronic(Jiangmen) Co., Ltd

六、产品规格表示方法 Product specification and model representation

LCH	0805	X7R	102	K	102	N	T	H
产品系列 Series	尺寸 Size	材质 Dielectric	标称容量 Capacitance	精度级别 Tolerance	脉冲电压 Impulse Voltage	端电极类型 Termination	包装方式 Packaging	厚度代号 Thickness
①	②	③	④	⑤	⑥	⑦	⑧	⑨

①产品系列 Series

代号	表示名称
L	利和兴
C	电容器
H	中高压产品

②尺寸规格 Size Specification(mm)

英制表示 BRITISH (EIA)	长×宽 (L×W) INCH	长×宽 (L×W) MM
0402	0.04×0.02	1.00×0.50
0603	0.06×0.03	1.60×0.80
0805	0.08×0.05	2.00×1.25
1206	0.12×0.06	3.20×1.60
1210	0.12×0.10	3.20×2.50
1808	0.18×0.08	4.50×2.00
1812	0.18×0.12	4.50×3.20

③介质种类 Dielectric Type

I类陶瓷介质	II类陶瓷介质
COG、COH	X7R、X7S、X5R、X6S

④静电容量 Capacitance

代号	表示值	静电容量	说明
R50	0.5	0.50pF	静电容量由3位字符表示。单位为皮法(pF)。第1位和第2位数字为有效数字，第3位数字表示有效数字后的0的个数。有小数点时以大写字母“R”表示。此时，所有数字均为有效数字。如果包含有任何不是“R”的字母，则表明该特指的品名是一个非标准的部件。 Nominal capacitance is represented by 3 digits, with the unit of picofarad (pF). The first and second digits are significant digits, and the third digit identifies the multiplier. When there is a decimal point, it is represented by a capital letter "R". At this time, all numbers are valid numbers. If it contains any letter other than "R", it indicates that the specified product name is a non-standard part.
1R0	1	1.0pF	
100	10	10pF	
102	10×10^2	1000pF	
104	10×10^4	100000pF	
...	

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⑤静容量公差 Capacitance Tolerance

代号	静容量公差	说明
B	±0.10pF	B、C、D 级误差适用于容量≤10pF 的产品
C	±0.25pF	
D	±0.5pF	
F	±1.0%	
G	±2.0%	
J	±5.0%	
K	±10%	
M	±20%	
S	+50% -20%	

⑥额定电压 Rated Voltage

代号	表示值	额定电压	说明
6R3	6. 3	DC6. 3V	
100	10×10^0	DC10V	额定电压前面两位数字代表电压数字， 第三位数字表示 0 的个数； R 代表小数点。
500	50×10^0	DC50V	The first and second digits are significant digits of the rated voltage, and the third digit identifies the multiplier; R represents the decimal point.
201	20×10^1	DC200V	
102	10×10^2	DC1000V	

⑦端电极类型 Termination Type

代号	端电极材料	注释
S	Ag 端电极	Ag/Ni/Sn
C	Cu 端电极	Cu/Resin
N	三层电镀端电极	Cu/Ni/Sn
R	软端子电极	Cu/树脂/Ni/Sn

⑧包装形式 Packing Code

代号	包装方式
T	纸带 Paper tape
S	塑胶带 Embossed tape
B	散包装 Bulk packaging

⑨厚度代码 Thickness Code

代号	厚度尺寸 (T)	代号	厚度尺寸 (T)	代号	厚度尺寸 (T)
A	0.10mm	G	0.70mm	S	1.80mm
B	0.20mm	H	0.80mm	U	2.00mm
C	0.30mm	J	1.00mm	V	2.50mm
D	0.40mm	L	1.25mm	W	3.00mm
E	0.50mm	M	1.40mm	X	3.70mm
F	0.60mm	P	1.60mm		

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七、温度系数/特性 Temperature Coefficient /Characteristics

介质种类 DIELECTRIC	参考温度点 REFERENCE TEMPERATURE POINT	标称温度系数 TEMPERATURE COEFFICIENT	工作温度范围 OPERATION TEMPERATURE RANGE
C0G	20°C	0±30 ppm/°C	-55°C ~ 125°C
C0H	20°C	0±60 ppm/°C	-55°C ~ 125°C
X5R	20°C	±15%	-55°C ~ 85°C
X6S	20°C	±22%	-55°C ~ 105°C
X7R	20°C	±15%	-55°C ~ 125°C
X7S	20°C	±22%	-55°C ~ 125°C

备注：I类电容器标称温度系数和允许偏差是采用温度在 20°C 和 85°C 之间的电容量变化来确定的，而II类电容器标称温度系数是按照工作范围之间的电容量相对 20°C 的电容量变化来确定的。

Note: Nominal temperature coefficient and allowed tolerance of class I are decided by the changing of the capacitance between 20°C and 85°C. Nominal temperature coefficient of class II are decided by the capacitance change at the testing temperature to 20°C.

八、中高压产品范围、尺寸、厚度 Product Range、Size & Thickness

① I类介质电容范围 (NPO)

温度特性: C0G (0 ± 30ppm/°C)\C0H (0 ± 60ppm/°C) 工作温度范围: -55°C ~ 125°C

T.C	COG、COH															
	0402		0603			0805				1206						
规格尺寸	100	250	100	200	250	100	250	500	630	1000	100	250	500	1000	1500	2000
额定电压 (V)																
0.5pF (0R5)	E	E	H	H	H	G	G	H	H	L						
1.0pF (1R0)	E	E	H	H	H	G	G	H	H	L						
1.2pF (1R2)	E	E	H	H	H	G	G	H	H	L						
1.5pF (1R5)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
1.8pF (1R8)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
2.2pF (2R2)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
2.6pF (2R6)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
3.0pF (3R0)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
3.3pF (3R3)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
4.0pF (4R0)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
4.7pF (4R7)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
5.0pF (5R0)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
5.6pF (5R6)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
6.0pF (6R0)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
6.8pF (6R8)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
7.0pF (7R0)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
8.0pF (8R0)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
8.2pF (8R2)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
9.0pF (9R0)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
10pF (100)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
12pF (120)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
15pF (150)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
18pF (180)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
20pF (200)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
22pF (220)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
27pF (270)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
30p (300)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
33pF (330)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
39pF (390)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
47pF (470)	E	E	H	H	H	G	G	H	H	L	G	G	H	J	J	J
56pF (560)	E		H	H	H	G	G	H	H	L	G	G	H	J	J	J
68pF (680)	E		H	H	H	G	G	H	H		G	G	H	J	L	L

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T.C	COG、COH															
	0402		0603			0805					1206					
规格尺寸	100	250	100	200	250	100	250	500	630	1000	100	250	500	1000	1500	2000
额定电压(V)																
82pF (820)	E		H	H	H	G	G	H	H		G	G	H	J	L	L
91pF (910)	E		H	H	H	G	G	H	H		G	G	H	J	L	L
100pF (101)	E		H	H	H	G	G	H	H		G	G	H	J	L	L
120pF (121)			H	H	H	G	G	H	H		G	G	J	J		
130pF (131)			H	H	H	G	H		L		G	G	J	J		
150pF (151)			H	H	H	G	H		L		G	G	J	L		
160pF (161)			H	H	H	G	H		L		G	G	J	L		
180pF (181)			H	H	H	G	H		L		G	G	J	L		
200pF(201)			H	H	H	G	H		L		G	G	J	L		
220pF(221)			H	H	H	G	H		L		G	G	J	L		
240pF(241)			H	H	H	G	H		L		G	G	J	L		
250pF(251)			H	H	H	G	H		L		G	G	J	L		
270pF(271)			H	H	H	G	H		L		G	G	J	L		
300pF(301)			H	H	H	G	H		L		G	G	J	L		
330pF(331)			H	H	H	G	H		L		G	G	J	L		
360pF(361)			H	H	H	G	H				G	G	J			
390pF(391)			H	H	H	G	H				G	G	J			
430pF(431)			H	H	H	G	H				G	G	J			
470pF(471)			H	H	H	G	H				G	G	J			
500pF(501)			H	H	H	G	H				G	H	L			
510pF (511)			H	H	H	G	H				G	H	L			
560pF(561)			H	H	H	G	H				G	H	L			
620pF(621)			H			G	H				G	H	L			
680pF(681)			H			G	H				G	H	L			
750pF(751)			H			G	H				G	H	L			
820pF(821)			H			G	H				G	H	L			
910pF (911)			H			G	H				G	H	L			
1.0nF (102)			H			G	H				H	H	L			
1.2nF (122)						G					H					
1.3nF (132)						G					H					
1.5nF (152)						G					H					
1.8nF (182)						G					H					
2.0nF (202)											H					
2.2nF(222)											H					



T.C	COG、COH														
规格尺寸	1210				1808				1812						
额定电压(V)	250	500 630	1000	1500 2000	500 630	1000	1500 2000	3000	200	250	500 630	1000	1500	2000	3000
10pF (100)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
12pF (120)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
15pF (150)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
18pF (180)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
20pF (200)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
22pF (220)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
27pF (270)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
30pF (300)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
33pF (330)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
39pF (390)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
47pF (470)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
56pF (560)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
68pF (680)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
82pF (820)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
91pF (910)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
100pF (101)	L	L	L	L	P	P	P	P	L	L	L	P	P	P	P
120pF (121)	L	L	L	L	P	P	P		L	L	L	P	P	P	
130pF (131)	L	L	L	L	P	P	P		L	L	L	P	P	P	
150pF (151)	L	L	L	L	P	P	P		L	L	L	P	P	P	
160pF (161)	L	L	L	L	P	P	P		L	L	L	P	P	P	
180pF (181)	L	L	L	L	P	P	P		L	L	L	P	P	P	
200pF (201)	L	L	L	L	P	P	P		L	L	L	P	P	P	
220pF (221)	L	L	L	L	P	P	P		L	L	L	P	P	P	
240pF (241)	L	L	L		P	P			L	L	L	P	P	P	
250pF (251)	L	L	L		P	P			L	L	L	P	P	P	
270pF (271)	L	L	L		P	P			L	L	L	P	P	P	
300pF (301)	L	L	L		P	P			L	L	L	P	P	P	
330pF (331)	L	L	L		P	P			L	L	L	P	P	P	
360pF (361)	L	L	L		P	P			L	L	L	P			
390pF (391)	L	L	L		P	P			L	L	L	P			
430pF (431)	L	L	L		P	P			L	L	L	P			
470pF (471)	L	L	L		P	P			L	L	L	P			

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T.C	COG、COH														
规格尺寸	1210				1808				1812						
额定电压(V)	250	500 630	1000	1500 2000	500 630	1000	1500 2000	3000	200	250	500 630	1000	1500	2000	3000
500pF (501)	L	L	L		P	P			L	L	L	P			
510pF (511)	L	L	L		P	P			L	L	L	P			
560pF (561)	L	L	L		P	P			L	L	L	P			
620pF (621)	L	L	L		P	P			L	L	L				
680pF (681)	L	L	L		P	P			L	L	L				
750pF (751)	L	L			P	P			L	L	L				
820pF (821)	L	L			P	P			L	L	L				
910pF (911)	L	L			P	P			L	L	L				
1.0nF (102)	L	L			P	P			L	L	L				
1.2nF (122)	L	L			P				L	L	L				
1.3nF (132)	L	L			P				L	L	L				
1.5nF (152)	L	L			P				L	L	L				
1.8nF (182)	L	P			P				L	L	L				
2.0nF (202)	L	P			P				L	L	L				
2.2nF (222)	L	P			P				L	L	L				
2.7 nF (272)	L				P				L	L					
3.3 nF (332)					P				L	L					
3.9 nF (392)					P				L	L					
4.7 nF (472)					P				L	L					
5.6 nF (562)									L	L					
6.8 nF (682)									L	L					
8.2 nF (822)									L	L					
10 nF (103)									L	L					
12 nF (123)									L	L					
15 nF (153)									L	L					
22 nF (223)									L	L					
27 nF (273)									L	L					
33 nF (333)									L	L					
39 nF (393)									L	L					
47 nF (473)									L	L					
56 nF (563)									L	L					
68 nF (683)									L	L					

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T.C	COG、COH														
规格尺寸	1210				1808				1812						
额定电压(V)	250	500 630	1000	1500 2000	500 630	1000	1500 2000	3000	200	250	500 630	1000	1500	2000	3000
82 nF (823)									L	L					
100nF (104)									L	L					

② II类介质电容范围 (X7R)

温度特性: X7R (±15%) 工作温度范围: -55°C ~ 125°C

T.C	X7R															
规格尺寸	0603			0805					1206							
额定电压 V	100	200	250	100	200	250	500	630	100	200	250	500	630	1000	2000	2500
100pF (101)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
120pF (121)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
150pF (151)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
180pF (181)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
220pF (221)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
270pF (271)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
330pF (331)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
390pF (391)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
470pF (471)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
560pF (561)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
680pF (681)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
820pF (821)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
1.0nF (102)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	L
1.2nF (122)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	P
1.5nF (152)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	P
1.8nF (182)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	P
2.2nF (222)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	P
2.7nF (272)	H	H	H	H	H	H	H	H	H	H	H	H	H	L	L	P
3.3nF (332)	H	H	H	H	H	H	L	L	H	H	H	L	L	L	L	
3.9nF (392)	H	H	H	H	H	H	L	L	H	H	H	L	L	L	L	
4.7nF (472)	H	H	H	H	H	H	L	L	H	H	H	L	L	L	L	
5.6nF (562)	H	H	H	H	H	H	L	L	H	H	H	L	L	L	L	

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T.C	X7R															
规格尺寸	0603			0805				1206								
额定电压 V	100	200	250	100	200	250	500	630	100	200	250	500	630	1000	2000	2500
6.8nF (682)	H	H	H	H	H	H	L	L	H	H	H	L	L	L		
8.2nF (822)	H	H	H	H	H	H	L	L	H	H	H	L	L	L		
10nF (103)	H			H	H	H	L	L	H	H	H	L	L	L		
12nF (123)	H			H	H	H			H	H	H	L	L			
15nF (153)	H			H	H	H			H	H	H	L	L			
18nF (183)	H			H	H	H			H	H	H	L	L			
22nF (223)	H			H	L	L			H	H	H	L	L			
27nF (273)	H			H	L	L			H	H	H	L	L			
33nF (333)	H			H	L	L			H	L	L	L	L			
39nF (393)	H			H					H	L	L	L	L			
47nF (473)	H			H					H	L	L	P	P			
56nF (563)	H			L					H	L	L					
68nF (683)	H			L					L	L	L					
82nF (823)	H			L					L	L	L					
100nF (104)	H			L					L	L	L					
120nF (124)				L					L	L	L					
150nF (154)				L					L	L	L					
180nF (184)				L					L	P	P					
220nF (224)				L					L	P	P					
270nF (274)									L							
330nF (334)									L							
390nF (394)									P							
470nF (474)									P							
560nF (564)									P							
680nF (684)									P							
820nF (824)									P							
1.0μF (105)									P							

T. C	X7R															
规格尺寸	1210					1808					1812					
额定电压 V	100	250	500 630	10 00	1500 2000	500 630	1000	1500 2000	2500	3000	200 250	500 630	1000	1500	2000	3000
100pF (101)	L	L	L	L	L											
120pF (121)	L	L	L	L	L											
150pF (151)	L	L	L	L	L	P	P	P	P	P						
180pF (181)	L	L	L	L	L	P	P	P	P	P						
220pF(221)	L	L	L	L	L	P	P	P	P	P						
270pF(271)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
330pF(331)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
390pF(391)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
470pF(471)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
560pF(561)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
680pF(681)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
820pF(821)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
1.0nF (102)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
1.2nF (122)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
1.5nF (152)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
1.8nF (182)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
2.2nF (222)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
2.7nF (272)	L	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P
3.3nF (332)	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P	P
3.9nF (392)	L	L	L	L	P	P	P	P	P	P	P	P	P	P	P	P
4.7nF (472)	L	L	L	P	P	P	P	P	P	P	P	P	P	P	P	P
5.6nF (562)	L	L	L	P	P	P	P	P			P	P	P	P	P	P
6.8nF (682)	L	L	L	P	P	P	P				P	P	P	P	P	P
8.2nF (822)	L	L	L	P	P	P	P				P	P	P	P	P	P
10nF (103)	L	L	L	P	P	P	P				P	P	P	P	P	P
12nF (123)	L	L	L	P	P	P	P				P	P	P			
15nF (153)	L	L	L	P		P	P				P	P	P			
18nF (183)	L	L	L	P		P	P				P	P	P			
22nF (223)	L	L	L	P		P					P	P	P			
27nF (273)	L	L	L	P		P					P	P	P			
33nF (333)	L	L	L			P					P	P	P			
39nF (393)	L	L	L			P					P	P	P			
47nF (473)	L	L	L			P					P	P	P			
56nF (563)	L	L	L								P	P	S			
68nF (683)	L	L	L								P	P	U			

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T. C	X7R															
	1210					1808					1812					
额定电压 V	100	250	500 630	10 00	1500 2000	500 630	1000	1500 2000	2500	3000	200 250	500 630	1000	1500	2000	3000
82nF (823)	L	L	P								P	P				
100nF (104)	L	L	P								P	P				
120nF (124)	L	L	P								P	P				
150nF (154)	L	L									P	P				
180nF (184)	L	P									P	P				
220nF (224)	L	P									P	P				
270nF (274)	P										P					
330nF (334)	P										P					
390nF (394)	P										P					
470nF (474)	P										P					
560nF (564)	P										P					
680nF (684)	P															
820nF (824)	P															
1.0μF (105)	P															

备注：可根据客户的特殊要求设计符合客户需求的产品。

Note: We can design according to customer special requirements

九、包装 Package

①产品厚度和包装数量 Thickness and Packing amount

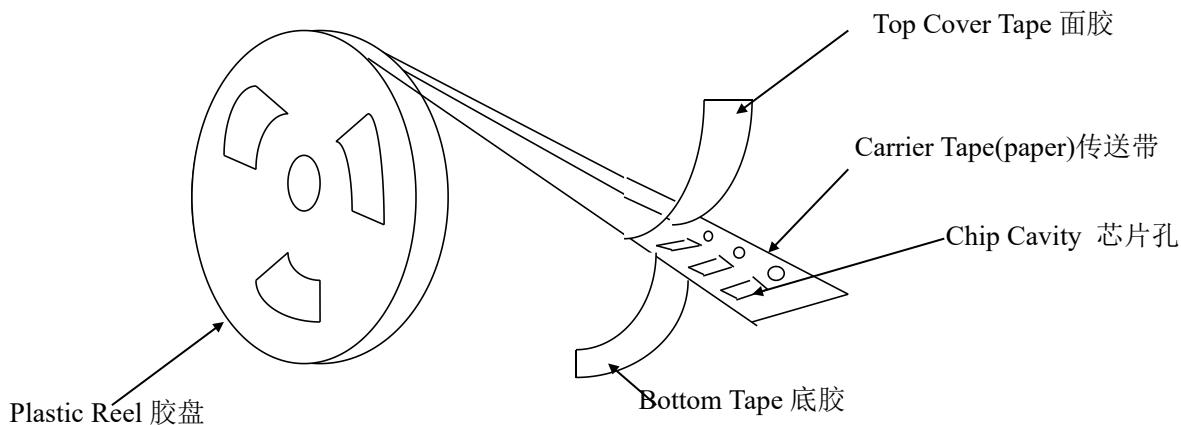
尺寸 Size	厚度代号 Thickness (mm)/Code		纸带 7" Reel Paper Tape	胶带 7" Reel Embossed Tape
			Standard Qty(pcs)	Standard Qty(pcs)
0402	0.50±0.05	E(C < 105)	10,000	-----
0402	0.50±0.20	E(C ≥ 105)	10,000	-----
0603	0.80±0.10	H	4000	-----
0805	0.70±0.10	G	4000	-----
	0.80±0.10	H	4000	-----
0805 1206	1.25±0.20	L	-----	3000
	0.70±0.10	G	4000	
	0.80±0.10	H	4000	
1206	1.00±0.10	J	-----	3000
1210	1.25±0.20	L	-----	3000
	1.60±0.20	P	-----	2000
	1.25±0.20	L	-----	2000
1210	1.60±0.20	P	-----	2000
1812	2.00±0.20	U	-----	2000
	2.50±0.30	V	-----	1000
	1.25±0.20	L	-----	1000
1812	1.60±0.20	P	-----	1000
	2.00±0.20	U	-----	1000
	2.50±0.30	V	-----	1000
	3.20±0.40		-----	1000
	1.25±0.20	L	-----	1000

② 带式圆盘包装 Tape and reel package

带式圆盘包装在高速 SMT 生产中广泛应用.典型的直径为 180mm(7 英寸)的圆盘可以包装 1500-15000 粒电容, 直径为 330mm(13 英寸)的圆盘可以包装 10000-50000 粒电容.带式圆盘包装包括纸带包装、胶带包装两种方式。

Tape and reel packaging is currently the most popular system for high-speed SMT production, A typical 180mm(7inch)diameter reel contains 1500 to 15,000 capacitors,330mm(13inch)diameter reel contains 10,000 to 50,000 capacitors, Tape and reel packaging comprises paper tapes and embossed tapes.

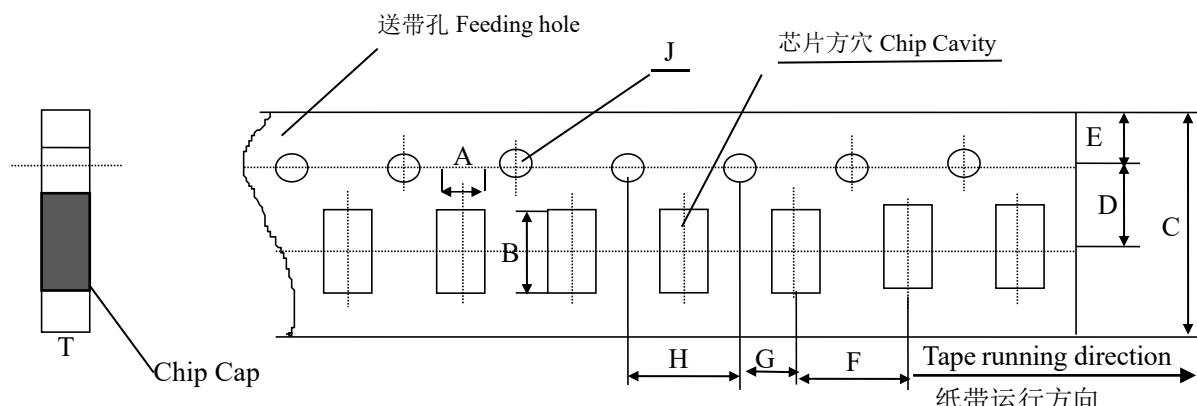
③ 纸带卷盘结构 Paper Taping



④ 纸带标准 Paper Tape Specifications

适合 0402、0603、0805、1206 常规产品的纸带尺寸

Dimensions of paper taping for 0402, 0603, 0805, 1206 types.

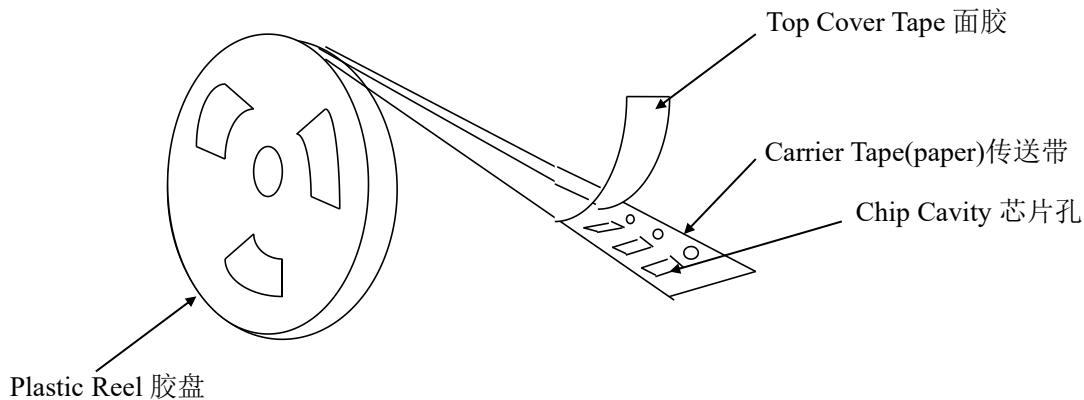


代号 Code 纸带规格 Paper size	A	B	C	D*	E	F	G*	H	J	T
0402	0.65± 0.10	1.15± 0.10	8.00± 0.10	3.50± 0.05	1.75± 0.10	2.00± 0.05	2.00± 0.05	4.00±0.1 0	1.50 -0/+0.10	0.80 Below
0603	1.10 ±0.10	1.90 ±0.10	8.00 ±0.10	3.50 ±0.05	1.75 ±0.10	4.00 ±0.10	2.00 ±0.10	4.00 ±0.10	1.50 -0/+0.10	1.10 Max
0805	1.45 ±0.15	2.30 ±0.15	8.0 ±0.15	3.50 ±0.05	1.75 ±0.10	4.00 ±0.10	2.00 ±0.10	4.00 ±0.10	1.50 -0/+0.10	1.10 Max
1206	1.80 ±0.20	3.40 ±0.20	8.00 ±0.20	3.50 ±0.05	1.75 ±0.10	4.00 ±0.10	2.00 ±0.10	4.00 ±0.10	1.50 -0/+0.10	1.10 Max

注意：*表示此处对尺寸的要求非常精确。

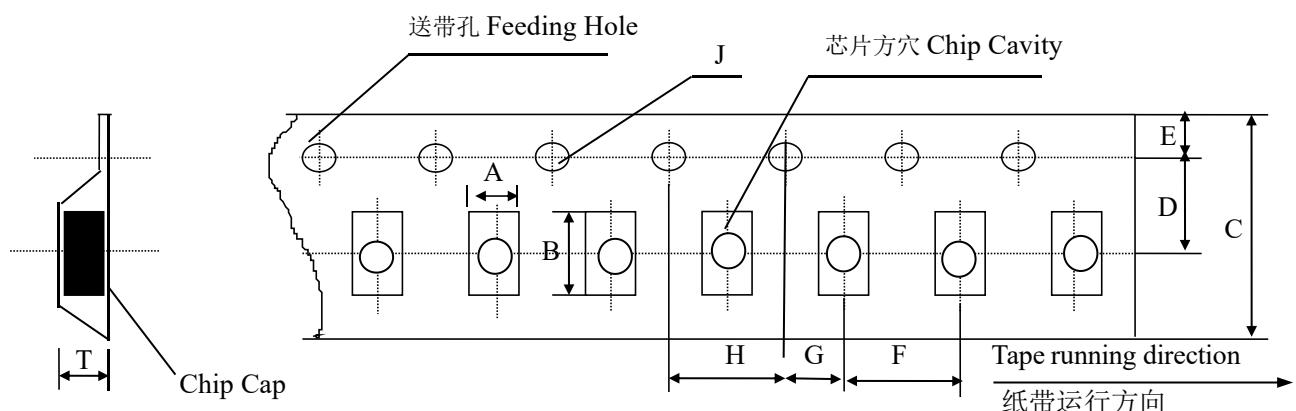
Note: The place with “*” means where needs exactly dimensions

⑤ 塑胶卷盘结构 Embossed Taping



※ 塑胶带尺寸结构(适合‘0805~1812’型产品)

Dimensions of embossed taping for 0805~1812 type

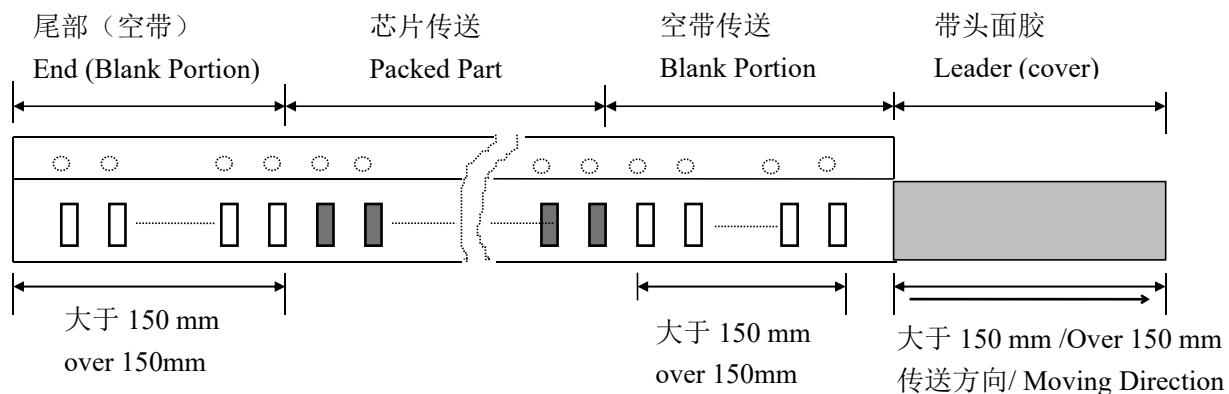


規格 Tapesize	A	B	C	D*	E	F	G*	H	J	T
0805	1.55 ± 0.20	2.35 ± 0.20	8.00 ± 0.20	3.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	4.00 ± 0.10	1.50 $-0/+0.10$	1.50 Max
1206	1.95 ± 0.20	3.60 ± 0.20	8.00 ± 0.20	3.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	4.00 ± 0.1	1.50 $-0/+0.10$	1.85 Max
1210	2.70 ± 0.10	3.42 ± 0.10	8.00 ± 0.10	3.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	1.55 $-0/+0.10$	3.2 Max
1808	2.20 ± 0.10	4.95 ± 0.10	12.00 ± 0.10	5.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	1.50 $-0/+0.10$	3.0 Max
1812	3.66 ± 0.10	4.95 ± 0.10	12.00 ± 0.10	5.50 ± 0.05	1.75 ± 0.10	8.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	1.55 $-0/+0.10$	4.0 Max

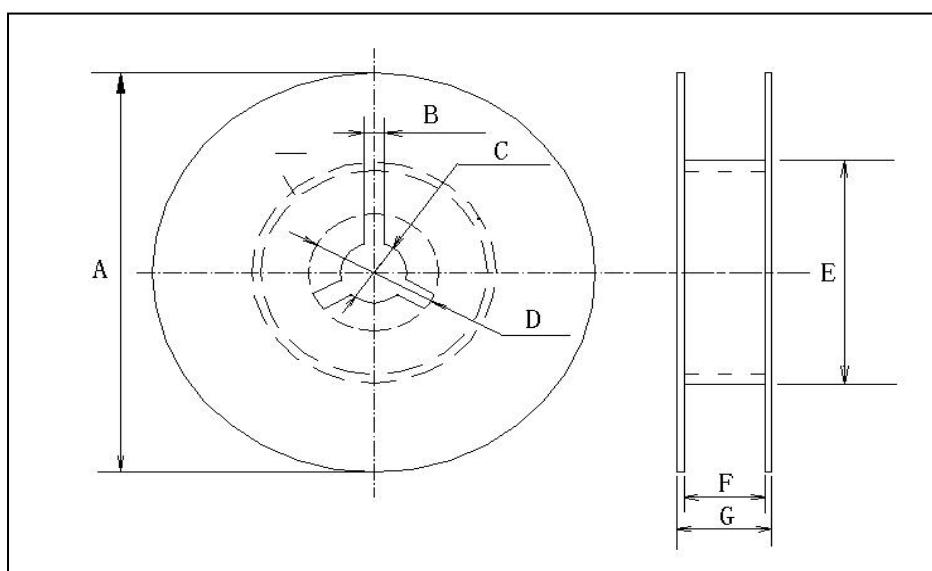
备注：*表示此处对尺寸的要求非常精确。

Note: The place with “**” means where needs exactly dimensions.

⑥ 传送带的前后结构 Front end and Back end Structure of Carrier Tape



a 卷盘尺寸 Reel Dimensions (unit: mm)



b 尺寸代码 (Code)

卷盘型号	A	B	C	D	E	F	G
7 REEL	$\phi 178 \pm 2.0$	3.0	$\phi 13 \pm 0.5$	$\phi 21 \pm 0.8$	$\phi 50$ 或更大 $\phi 50$ or more	10.0 ± 1.5	12max
13' REEL	$\phi 330 \pm 2.0$	3.0	$\phi 13 \pm 0.5$	$\phi 21 \pm 0.8$	$\phi 50$ 或更大 $\phi 50$ or more	10.0 ± 1.5	12max

⑦ 纸带性能 Performance of Taping

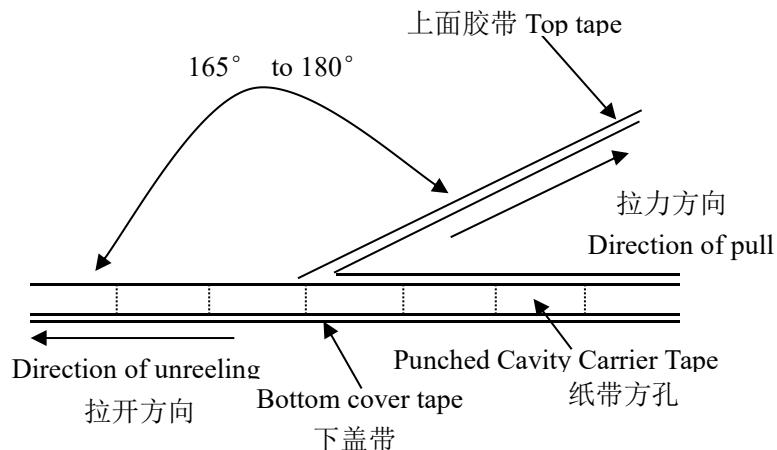


图 a

⑧纸带和上盖带的剥离强度 .Peeling Force of Carrier Tape and Top Cover Tape

(a) 纸带在伸直状态下应该能经受 1.02kg 的压力。

The paper tape shall be able to withstand a pressure of 1.02kg in the straight state

(b) 上盖带应该能经受 1.02kg 的压力。

The top cover tape should withstand 1.02kg of pull force

(c) 上盖带剥离强度 Peel Force of Top Cover Tape

除非有特殊规定，上盖带以 300mm/min 的速度，165~180°的角度（如图 a）剥离纸带时，剥离强度应该在 10~60g 之间。

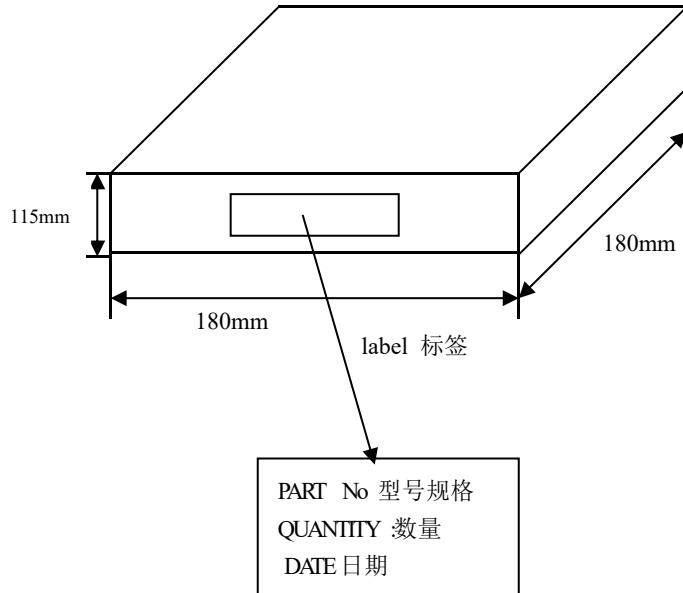
Unless otherwise specified, the peeling force of top cover tape shall be 10g to 60g when the top cover tape is pulled at a speed of 300mm/min with the angle between the taped during peeling and the direction of unreeeling maintained at 165 to 180°as shown in figure (a)

⑨ 外箱包装 Packing

小包装 The inner package

Quantity: 10 reels

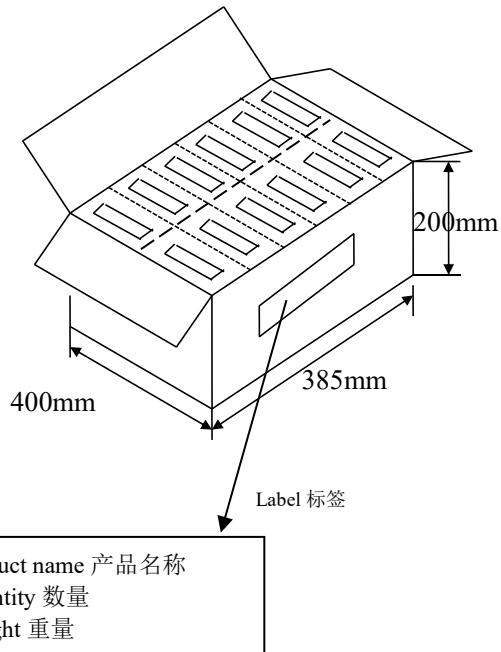
数量： 10 卷



大包装 The outer package

Quantity: 6 cases

数量： 6 盒



十、储存方法 Storage Methods

确保芯片可焊性良好的贮存期限为 6 个月(在包装好已交付的情况下)。

The guaranteed period for solderability is 6 months (Under deliver package condition).

储存条件/Storage conditions:

储存温度/Temperature 5~40°C

储存相对湿度/Relative Humidity 20~70%

十一、使用前的注意事项 Precautions For Use

多层片式瓷介电容器(MLCC)在短路或开路的电路中都有可能失效,在超出本承认书或相关说明书中所述使用的恶劣工作环境,或外界机械力超压作用下,电容芯片都有可能着火、燃烧甚至爆炸,所以在使用的时候,首先应考虑按本承认书的有关说明来进行,如有不明之处,请联系厂家咨询。

The Multi-layer Ceramic Capacitors (MLCC) may fail in a short circuit or in an open circuit mode when subjected to severe conditions of electrical environment and / or mechanical stress beyond the specified “rating” and specified “conditions” in the specification, which

will result in burn out, flaming or explosion in the worst case. Following “precautions for “safety” and Application Notes shall be taken in your major consideration.

① 焊接的条件与相关图表 Soldering Profile

为避免因温度的突然变化而引起的芯片开裂或局部爆炸的现象发生,请按有关温度曲线图表来进行.(请参考附页中的图表)

To avoid the crack problem by sudden temperature change, follow the temperature profile in the related graph (refer to the graph in the enclosure page).

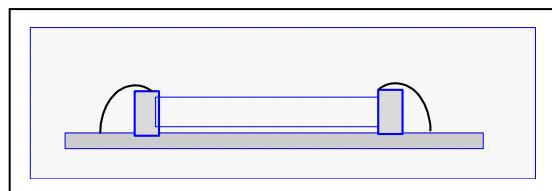
② 手工焊接 Manual Soldering

手工焊接很容易因为芯片局部受热不均而引起瓷体微裂或局部爆炸的现象,在焊接时,如果操作者不小心,会使烙铁头直接同电容芯片的瓷体部分接触,这样很容易使电容芯片因热冲击而受损或出现其他意外.因此,使用电烙铁手工焊接时应仔细操作,并对电烙铁的尖端的选择和尖端温度控制应多加小心.

Manual welding is easy to cause microcrack or partial cracking because of uneven heating of chip. The hot soldering iron tip comes into direct contact with the end terminations, and operator's careless may cause the tip of the soldering iron to come into direct contact with the ceramic body of the capacitor. Therefore the soldering iron must be handled carefully, and pay much attention to the selection of the soldering iron tip and temperature contact of the tip.

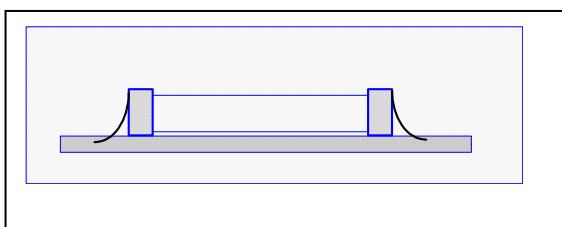
③ 适量的焊料 Optimum Solder Amount for Reflow Soldering

焊料过多
Too much solder



这样会因端头压力过大可能引起
芯片受损
Cracks tend to occur due to
large stress.

焊料太少
Not enough solder

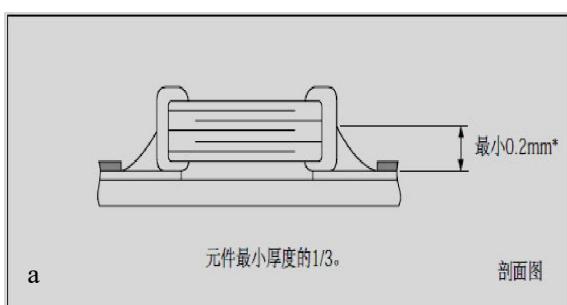


固定力量不足,可能会引起电容
芯片与线路接触不良
Weak holding force may cause
bad connection between the
capacitor and PCB

④ 推荐焊料用量 Recommended Soldering amounts

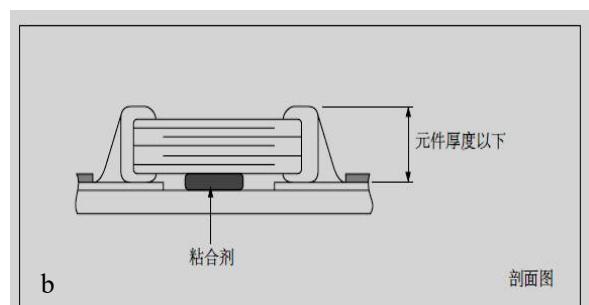
a.回流焊接的最佳焊料用量

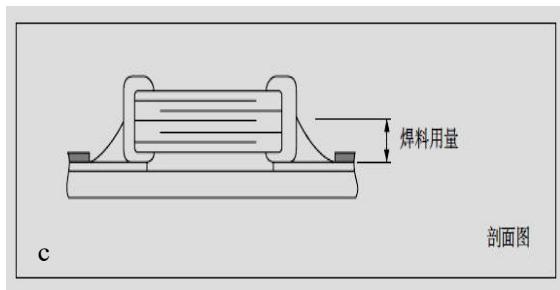
The optimal solder amounts for re-flow soldering



b.波峰焊接的最佳焊料用量

The optimal solder amounts for wave soldering



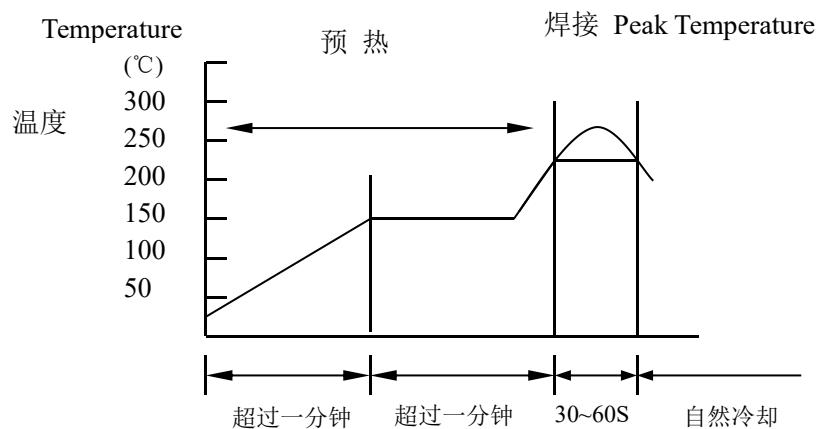


c. 使用烙铁返修时的最佳焊料量

The optimal solder amounts for reworking by using soldering iron

十二、推荐焊接温度曲线图 The temperature profile for soldering

(a) 回流焊接 (Re-flow soldering)

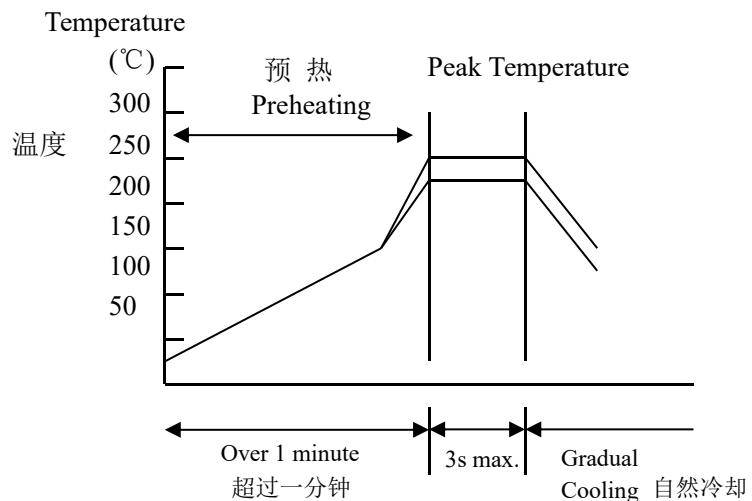


	Pb-Sn 焊接 Pb-Sn soldering	无铅焊接 Lead-free soldering
尖峰温度 Peak temperature	230°C ~ 250°C	240°C ~ 260°C

在预热时, 请将焊接温度与芯片表面温度之间的温差维持在 $T \leq 150^{\circ}\text{C}$ 。

While in preheating, please keep the temperature difference between soldering temperature and surface temperature of chips as: $T \leq 150^{\circ}\text{C}$.

(b) 波峰焊接 (Wave soldering)

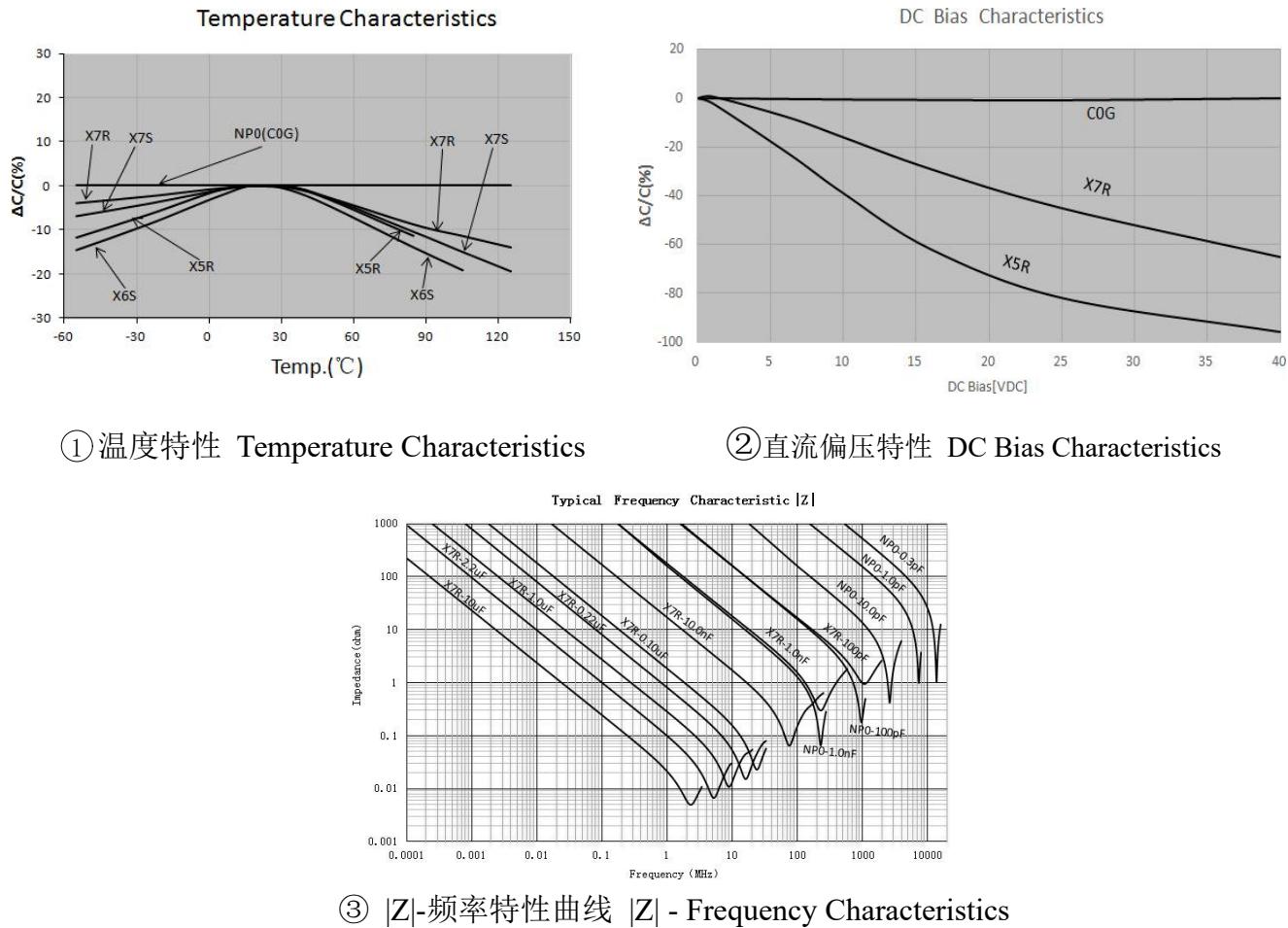


	Pb-Sn 焊接 Pb-Sn soldering	无铅焊接 Lead-free soldering
尖峰温度 Peak temperature	230°C ~ 260°C	240°C ~ 270°C

在预热时, 请将焊接温度与芯片表面温度之间的温差维持在 $T \leq 150^{\circ}\text{C}$ 。

While in preheating, please keep the temperature difference between soldering temperature and surface temperature of chips as: $T \leq 150^{\circ}\text{C}$.

十三、电气特性 Electrical Characteristics



十四、中高压电容器测试方法 Measurement Method for High Voltage MLCC

额定电压范围 Rated voltage Range	耐压性能的测试方法 Measuring Method
100V≤V _r <500V	施加额定电压的 200%, 5 秒, 最大电流不超过 50mA Applied Voltage: 200% Rated voltage for 5 second. Max.current should not exceed 50 mA.
500V≤V _r ≤1000V	施加额定电压的 150%, 5 秒, 最大电流不超过 50mA Applied Voltage: 150% Rated voltage for 5 second. Max..current should not exceed 50 mA.
1000V<V _r ≤5000V	施加额定电压的 120%, 5 秒, 最大电流不超过 50mA Applied Voltage: 120% Rated voltage for 5 seconds. Max.current should not exceed 50 mA.

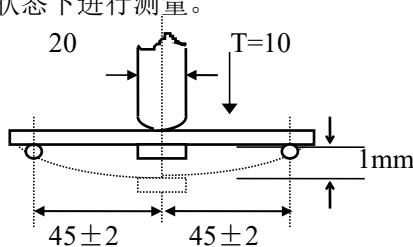
十五、性能测试方法

项目 Item	技术规格 Technical Specification		测 试 方 法 Test Method and Remarks			
容量 Capacitance	I类 Class I	应符合指定的误差级别 Should be within the specified tolerance.	标称容量 Capacitance	测试频率 Measuring Frequency	测试电压 Measuring Voltage	
			≤1000pF	1MHz±10%	1.0±0.2Vrms	
			>1000 pF	1KHz±10%		
损耗角正切 (DF, tan δ) Dissipation Factor	II类 Class II	应符合指定的误差级别 Should be within the specified tolerance.	测试温度: 25°C ±3°C Test Temperature: 25°C ±3°C C≤10μF: 测试频率: 1KHz±10% 测试电压: 1.0±0.2Vrms Test Frequency: 1KHz±10% Test Voltage: 1.0±0.2Vrms C>10μF X7R、X5R、X7S、X6S 测试频率: 120±24 Hz 测试电压: 0.5±0.1Vrms Test Frequency: 120±24 Hz Test Voltage: 0.5±0.1Vrms			
			DF 标称容量 Capacitance			
损耗角正切 (DF, tan δ) Dissipation Factor	I类 Class I	≤0.56%	Cr<5 pF	1MHz±10%	1.0±0.2Vrms	
		1.5[(150/Cr)+7]×10 ⁻⁴	5pF≤Cr<50 pF	1MHz±10%		
		≤0.10%	50pF≤Cr≤1000 pF	1MHz±10%		
		≤0.10%	>1000 pF	1KHz±10%		

利和兴电子元器件（江门）有限公司
 Lihexing electronic components(Jiangmen) Co., Ltd
 利容电子（江门）有限公司
 Lirong electronic(Jiangmen) Co., Ltd

项目 Item	技术规格 Technical Specification					测 试 方 法 Test Method and Remarks		
			≥50V	25V	16V	10V	6.3V	C≤10μF 测试频率: 1KHz±10% 测试电压: 1.0±0.2Vrms Test Frequency: 1KHz ± 10% Test Voltage: 1.0 ± 0.2Vrms
损耗角正切 (DF, tan δ) Dissipation Factor	X7R/X5R X7S/X6S (≥ 0402)		≤2.5% (C < 0.47μF) ≤5.0% (C ≥ 0.47μF)	≤3.5% (C < 0.47μF) ≤10.0% (C ≥ 0.47μF)	≤3.5% (C < 0.47μF) ≤10.0% (C ≥ 0.47μF)	≤5.0% (C < 0.15μF) ≤10.0% (C ≥ 0.15μF)	≤5.0% (C < 0.15μF) ≤10.0% (C ≥ 0.15μF)	
	II类 Class II	X7R/X5R X7S/X6S (< 0402)	≤3.5%	≤5.0%	≤5.0% (C < 0.047μF) ≤10% (C ≥ 0.047μF)	≤5.0% (C < 0.047μF) ≤10% (C ≥ 0.047μF)	≤5.0% (C < 0.047μF) ≤10% (C ≥ 0.047μF)	C>10μF X7R、X5R、 X7S、X6S 测试频率: 120±24 Hz 测试电压: 0.5±0.1Vrms Test Frequency: 120 ± 24 Hz Test Voltage: 0.5 ± 0.1Vrms Z5U: 测试频率: 1 ± 0.1KHz 测试电压: 0.5±0.05Vrms Test Frequency: 1 ± 0.1KHz Test Voltage: 0.5 ± 0.05Vrms
绝缘电 阻 (IR) Insulation Resistance	I类 Class I	C≤10nF, Ri≥50000M Ω C>10nF, Ri•C _R ≥500S						测试电压: 额定电压 测试时间: 60±5 秒 测试湿度: ≤75% 测试温度: 25°C ± 3°C 测试充放电电流: ≤50mA Measuring Voltage: Rated Voltage Duration: 60±5s Test Humidity: ≤75% Test Temperature: 25°C ± 3°C Test Current: ≤50mA
	II类 Class II	C≤25nF, Ri≥10000M Ω C>25nF, Ri•C _R >100S						

介质耐电度 (DWV) Dielectric Withstanding Voltage	不应有介质被击穿或损伤 No breakdown or damage.	<p>测量电压: I 类: 300%额定电压 II类: 250%额定电压 时间: 1~5 秒 充/放电电流: 不应超过 50mA (这部分说明不包括中高压 MLCC)</p> <p>Measuring Voltage: Class I :300% Rated voltage Class II :250% Rated voltage Duration: 1~5s Charge/ Discharge Current: 50mA max. (This method excludes high-voltage MLCC)</p>
项目 Item	技术规格 Technical Specification	测 试 方 法 Test Method and Remarks

可焊性 Solderability	上锡率应大于 95% 外观: 无可见损伤. At least 95% of the terminal electrode is covered by new solder. Visual Appearance: No visible damage.			将电容在 80~120°C 的温度下预热 10~30 秒. Preheating conditions: 80 to 120°C; 10~30s.
				有铅焊料: (Sn/Pb: 63/37) 浸锡温度: 235±5°C 浸锡时间: 2±0.5s Solder Temperature: 235±5°C Duration: 2±0.5s
耐焊接热 Resistance to Soldering Heat	项目 Item NPO 至 SL NPO to SL X7R/X5RX 7S/X6S			无铅焊料: (LeadFree) 浸锡温度: 245±5°C 浸锡时间: 2±0.5s Solder Temperature: 245±5°C Duration: 2±0.5s
	ΔC/C $\leq \pm 0.5\%$ 或 $\pm 0.5\text{PF}$, 取较大值 $\leq \pm 0.5\%$ or $\pm 0.5\text{PF}$, whichever is larger			将电容在 100~200°C 的温度下预热 10±2 分钟. Preheating conditions: 100 to 200°C; 10±2min.
	DF 同初始标准 Same to initial value.			浸锡温度: 265±5°C 浸锡时间: 10±1s 然后取出溶剂清洗干净, 在 10 倍以上的显微镜底下观察 放置时间: 24±2 小时 放置条件: 室温 Solder Temperature: 265±5°C Duration: 10±1s
	IR 同初始标准 Same to initial value.			Clean the capacitor with solvent and examine it with a 10X(min.) microscope. Recovery Time: 24±2h Recovery condition: Room temperature
抗弯曲强度 Bending Strength	外观: 无可见损伤 上锡率: $\geq 95\%$ Appearance: No visible damage. At least 95% of the terminal electrode is covered by new solder.			试验基板: PCB 弯曲深度: 1mm 施压速度: 0.5mm/sec. 单位: mm 应在弯曲状态下进行测量。
	Δ C/C $\leq \pm 10\%$			 Test Board: PCB Warp: 1mm Speed: 0.5mm/sec. Unit: mm The measurement should be made with the board in the bending position.
	技术规格 Technical Specification		测 试 方 法 Test Method and Remarks	

温度循环 Temperature Cycle	$\Delta C/C:$ I 类: $\leq \pm 1\%$ 或 $\pm 1\text{pF}$, 取两者中最大者 II 类: X7R\X7S\X6S\X5R: $\leq \pm 10\%$ E,F: $\leq \pm 20\%$ Class I : $\leq \pm 1\%$ or $\pm 1\text{pF}$, whichever is larger. Class II : X7R\X7S\X6S\X5R: $\leq \pm 10\%$ E,F: $\leq \pm 20\%$	预处理* (2类) : 上限类别温度, 1 小时 恢复: $24 \pm 1\text{h}$ 初始测量 循环次数: 5 次,一个循环分以下 4 步: <table border="1"> <thead> <tr> <th>阶段</th><th>温度 (°C)</th><th>时间 (分钟)</th></tr> </thead> <tbody> <tr> <td>第 1 步</td><td>下限温度 (NPO/X7R/X7S/X6S/X5R: -55°C)</td><td>30</td></tr> <tr> <td>第 2 步</td><td>常温 (+20)</td><td>2~3</td></tr> <tr> <td>第 3 步</td><td>上限温度(NPO/X7R/X7S: +125°C X6S:+105°C)</td><td>30</td></tr> <tr> <td>第 4 步</td><td>常温 (+20)</td><td>2~3</td></tr> </tbody> </table> 试验后放置 (恢复) 时间: $24 \pm 2\text{h}$ Preheating conditions: Up-Limit temperature, 1h Recovery time: $24 \pm 1\text{h}$ Initial Measurement Cycling Times: 5 times, 1 cycle, 4 steps: <table border="1"> <thead> <tr> <th>Step</th><th>Temperature (°C)</th><th>Time(min)</th></tr> </thead> <tbody> <tr> <td>1</td><td>Low-Limit temp. (NPO/X7R/X7S/X6S/X5R: -55°C)</td><td>30</td></tr> <tr> <td>2</td><td>Normal temp. (+20)</td><td>2~3</td></tr> <tr> <td>3</td><td>Up-Limittemp. (NPO/X7R/X7S: +125°C X6S:+105°C)</td><td>30</td></tr> <tr> <td>4</td><td>Normal temp. (+20)</td><td>2~3</td></tr> </tbody> </table> Recovery time after test: $24 \pm 2\text{h}$	阶段	温度 (°C)	时间 (分钟)	第 1 步	下限温度 (NPO/X7R/X7S/X6S/X5R: -55°C)	30	第 2 步	常温 (+20)	2~3	第 3 步	上限温度(NPO/X7R/X7S: +125°C X6S:+105°C)	30	第 4 步	常温 (+20)	2~3	Step	Temperature (°C)	Time(min)	1	Low-Limit temp. (NPO/X7R/X7S/X6S/X5R: -55°C)	30	2	Normal temp. (+20)	2~3	3	Up-Limittemp. (NPO/X7R/X7S: +125°C X6S:+105°C)	30	4	Normal temp. (+20)	2~3
阶段	温度 (°C)	时间 (分钟)																														
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1	Low-Limit temp. (NPO/X7R/X7S/X6S/X5R: -55°C)	30																														
2	Normal temp. (+20)	2~3																														
3	Up-Limittemp. (NPO/X7R/X7S: +125°C X6S:+105°C)	30																														
4	Normal temp. (+20)	2~3																														
温度: $40 \pm 2\text{°C}$ 湿度: 90~95%RH 时间: 500 小时 放置条件: 室温 放置时间: 24 小时(I 类); 48 小时(II 类) Temperature: $40 \pm 2\text{°C}$ Humidity: 90~95%RH Duration: 500h Recovery conditions: Room temperature Recovery Time: 24h (Class1) or 48h (Class2)																																
潮湿试验 Moisture Resistance	$\Delta C/C:$ I 类: $\leq \pm 2\%$ 或 $\pm 1\text{pF}$, 取两者之中较大者 II 类:X7R\X7S\X6S\X5R: $\leq \pm 10\%$ E,F: $\leq \pm 30\%$ Class I : $\leq \pm 2\%$ or $\pm 1\text{pF}$, whichever is larger. Class II : X7R\X7S\X6S\X5R: $\leq \pm 10\%$ E,F: $\leq \pm 30\%$	DF	≤ 2 倍初始标准 Not more than twice of initial value.																													
	$\Delta C/C:$ I 类: $R_i \geq 2500M\Omega$ 或 $R_i \cdot C_r \geq 25S$ 取两者之中较小者. Class I : $R_i \geq 2500M\Omega$ 或 $R_i \cdot C_r \geq 25S$ whichever is smaller. II 类: $R_i \geq 1000M\Omega$ 或 $R_i \cdot C_r \geq 25S$ 取两者之中较小者. Class II : $R_i \geq 1000M\Omega$ 或 $R_i \cdot C_r \geq 25S$ whichever is smaller.	IR																														
		外观: 无损伤 Appearance: No visible damage.																														

项目 Item	技术规格 Technical Specification		测 试 方 法 Test Method and Remarks
中高压产品 寿命试验 Middle &high voltage Life Test	$\Delta C/C$	I 类: $\leq \pm 2\%$ 或 $\pm 1\text{pF}$ 取两者之中较大者 II 类 : X7R\X7S\X6S\X5R: $\leq \pm 20\%$ E,F: $\leq \pm 30\%$ Class I : $\leq \pm 2\%$ or $\pm 1\text{pF}$, whichever is larger. Class II : X7R\X7S\X6S\X5R: $\leq \pm 20\%$ E,F: $\leq \pm 30\%$	中高压产品: 100V \leq 额定电压 $<$ 500V: 2 倍工作电压 500V \leq 额定电压 \leq 1000V: 1.5 倍工作电压 额定电压 $>$ 1000V: 1.2 倍工作电压 时间: 100 小时 *温度: 125°C (NPO、X7R) 85°C (X5R) 充电电流: 不应超过 50mA 放置条件: 室温
		≤ 2 倍初始标准 Not more than twice of initial value	放置时间: 24 小时 (I类) 或 48 小时 (II类), Mid-High Voltage Capacitor: 100V \leq Rated Voltage $<$ 500V: $2 \times$ Rated Voltage 500V \leq Rated Voltage \leq 1000V: $1.5 \times$ Rated Voltage Rated Voltage $>$ 1000V: $1.2 \times$ Rated Voltage Duration: 100h *Temperature: 125°C (NPO、 X7R) 85°C (X5R) Charge/ Discharge Current: 50mA max. Recovery Conditions: Room Temperature Recovery Time: 24h (Class 1), or 48h (Class2)
	IR	I 类 : $R_i \geq 4000M\Omega$ 或 $R_i \cdot C_R \geq 40S$ 取两者之中较小者. Class I : $R_i \geq 4000M\Omega$ 或 $R_i \cdot C_R \geq 40S$ whichever is smaller	
	外观: 无损伤 Visual Appearance: No visible damage		

注解:

专门预处理 (仅对 2 类电容器) :

将电容器放在上限类别温度或按详细规范中可能规定的更高温度下经 1h 后, 接着在试验的标准大气条件下恢复 $24 \pm 1\text{h}$ 。

Note: Pretreatment (only for class2 capacitor)

Pretreatment (only for class2 capacitor) is a method to treat the capacitor before measurement. First, place the capacitor in the up-limit temperature or other specified higher temperature environment for 1hour. Then recovery the capacitor at standard atmospheric pressure conditions for $24 \pm 1\text{hours}$.